

L Number	Hits	Search Text	DB	Time stamp
1	2	"10079405"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:32
2	2	"09008081"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:35
3	2	5900675.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:42
4	19	("3290564" "4654248" "4893172" "4914551" "4942076" "5086337" "5216278" "5325265" "5338967" "5473119" "5481136" "5493153" "5572070" "5574630" "5610442" "5714803" "5744863" "5777386" "5786635").PN.	USPAT	2004/08/18 15:35
5	18	5900675.URPN.	USPAT	2004/08/18 15:36
6	8	("5239198" "5798564" "5869889" "5870289" "5900675" "5977633" "6229215" "6232667").PN.	USPAT	2004/08/18 15:38
7	12	5869889.URPN.	USPAT	2004/08/18 15:40
8	1044	(package or packaging or wiring or mounting or mount) and (chip or die or ic) near5 (cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:43
9	539	(package or packaging or wiring or mounting or mount) and (plural or plurality or multi or multiple or two or several) near3 (chip or die or ic) and (chip or die or ic or substrate) near2 (cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:45
10	3111	(package or packaging or wiring or mounting or mount) and (substrate or board or pwb or pcb or interposer) near6 (recess or recessed or cavity or depression) near4 (chip or ic or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:46
11	714	(package or packaging or wiring or mounting or mount) same (substrate or board or pwb or pcb or interposer) near3 (recess or recessed or cavity or depression) near2 (chip or ic or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:47
12	484	(package or packaging or wiring or mounting or mount) same (substrate or board or pwb or pcb or interposer) near3 (recess or recessed or cavity or depression) near2 (chip or ic or die) and (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:48
13	126	(package or packaging or wiring or mounting or mount) same (substrate or board or pwb or pcb or interposer) near3 (recess or recessed or cavity or depression) near2 (chip or ic or die) and (semiconductor or silicon) and (cte or thermal\$ near2 expan\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:54
14	519	(package or packaging or wiring or mounting or mount) same (substrate or board or pwb or pcb or interposer) with (chip or ic or die) with cte and (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:56

15	95	(package or packaging or wiring or mounting or mount) same (substrate or board or pwb or pcb or interposer) with (chip or ic or die) with cte with (warping or bending or warp or warpage or warped or bent or curving or curved or cavity or depression or convex or concave or flexing or deformed or deform or deforming or deformation) and (semiconductor or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 16:08
16	28	(package or packaging or wiring or mounting or mount) and (bga or solder near2 joint) near15 cte with (warping or bending or warp or warpage or warped or bent or curving or curved or cavity or depression or convex or concave or flexing or deformed or deform or deforming or deformation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 16:09
17	17	(US-6562662-\$ or US-6528179-\$ or US-5952719-\$ or US-6518666-\$ or US-6417027-\$ or US-6396159-\$ or US-6392143-\$ or US-4897918-\$ or US-6756663-\$ or US-5977633-\$).did. or (US-20030089978-\$ or US-20020050642-\$ or US-20020197771-\$ or US-20020155637-\$).did. or (WO-9704629-\$).did. or (JP-09162545-\$ or JP-09008081-\$).did.	USPAT; US-PGPUB; EPO; JPO	2004/08/18 16:12
18	9	("5136470" "5450286" "5571608" "5760465" "5773884" "5877043" "5987742" "6014317" "6027590").PN.	USPAT	2004/08/18 16:16
19	13	("5275889" "5550407" "5585672" "5744863" "5789820" "5886408" "5970319" "5981085" "6069023" "6108208" "6133071" "6144101" "6169328").PN.	USPAT	2004/08/18 16:19
20	7	("5181097" "5665795" "5683942" "5708300" "5726489" "5729051" "5841192").PN.	USPAT	2004/08/18 16:27
21	2	("5668405" "5835355").PN.	USPAT	2004/08/18 16:29
22	12	5977633.URPN.	USPAT	2004/08/18 16:29
23	28	("3248681" "3351700" "3399332" "4283464" "4491622" "4500605" "4577056" "4581680" "4712127" "4784974" "4811166" "4872047" "4888449" "4939316" "4961105" "5001546" "5015803" "5044074" "5073840" "5103292" "5213638" "5239131" "5241133" "5315155" "5409865" "5506446" "5578869" "5629835").PN.	USPAT	2004/08/18 16:31
24	6	5952719.URPN.	USPAT	2004/08/18 16:34
-	8087	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping or concave or recess or recessed) near8 (board or substrate or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:30
-	2037	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping or concave) near5 (board or substrate or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 15:40
-	1830	(package or packaging) and (warped or warping or concave) near5 (board or substrate or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 15:39
-	611	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping or concave) near5 (board or substrate or pcb or pwb) and solder near3 (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 15:41

-	393	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping) near3 (board or substrate or pcb or pwb) and solder near3 (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/07/28 09:49
-	5	("5994166" "6121689" "6137164" "6316838" "6437990" "2002/0079567" "2002/0079568").PN.		2004/07/27 17:03
-	425	(package or packaging or (chip or die or id) near2 (mounting)) and (warped or warping or warp or curved or curve or curving or concave) near (board or substrate or pcb or pwb or device) and solder near3 (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 12:00
-	289	(package or packaging or (chip or die or id) near2 (mounting)) and (bent or bending or bend or sag or sagging or sagged) near (board or substrate or pcb or pwb or device) and solder near3 (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:40
-	566	(package or packaging or (chip or die or id) near2 (mounting)) and (bent or bending or bend or sag or sagging or sagged) near2 (board or substrate or pcb or pwb or device) and solder near3 (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:03
-	277	((package or packaging or (chip or die or id) near2 (mounting)) and (bent or bending or bend or sag or sagging or sagged) near2 (board or substrate or pcb or pwb or device) and solder near3 (bump or ball)) not ((package or packaging or (chip or die or id) near2 (mounting)) and (bent or bending or bend or sag or sagging or sagged) near (board or substrate or pcb or pwb or device) and solder near3 (bump or ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 14:42
-	30	("4555151" "4907128" "4991927" "5089880" "5229960" "5247423" "5313416" "5343366" "5384690" "5435733" "5440171" "5471151" "5585675" "5620782" "5761795" "5776797" "5781415" "5798014" "5838546" "5927193" "5986886" "5992649" "6027958" "6049975" "6051877" "6061245" "6064217" "6086386" "6104089" "6121676").PN.	USPAT	2004/07/28 14:56
-	2497	(package or packaging or (chip or die or id) near2 (mounting)) and (deformation or deforming or deformed or deformable) near2 (board or substrate or pcb or pwb or device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:04
-	775	(package or packaging or (chip or die or id) near2 (mounting)) and (deformation or deforming or deformed or deformable) near (board or substrate or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:05
-	239	(package or packaging or (chip or die or id) near2 (mounting)) and (deformation or deforming or deformed or deformable) near (board or substrate or pcb or pwb) and (cte or thermal near expansion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:05
-	344	(package or packaging or (chip or die or id) near2 (mounting)) and (deformation or deforming or deformed or deformable or bent or bending or warp or warping or warped or sagging or sag or curved or concave) near3 (board or substrate or pcb or pwb) near15 (cte or thermal near expansion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/28 15:07
-	9	("3871015" "4801998" "5186383" "5269453" "5326794" "5346118" "5381307" "5400950" "5576362").PN.	USPAT	2004/07/28 15:26

-	13	("5275889" "5550407" "5585672" "5744863" "5789820" "5886408" "5970319" "5981085" "6069023" "6108208" "6133071" "6144101" "6169328").PN.	USPAT	2004/07/28 15:28
-	2588	(mount or mounting or package or packaging) near3 (board or substrate or pcb or pwb or interposer or carrier or chip or die or ic or component or device) near2 (warp or warping or bending or bent or curved or curving or curve or warped or bend or concave or convex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 13:47
-	436	(mount or mounting or package or packaging) near3 (board or substrate or pcb or pwb or interposer or carrier or chip or die or ic or component or device) near2 (warp or warping or warped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 13:47
-	90	(mount or mounting or package or packaging) near3 (board or substrate or pcb or pwb or interposer or carrier or chip or die or ic or component or device) near2 (warp or warping or warped or warpage) same (bga or ball near grid or solder near ball or solder near bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 14:24
-	5	("5994166" "6121689" "6137164" "6316838" "6437990" "2002/0079567" "2002/0079568").PN.	USPAT	2004/08/12 14:04
-	153	(bga or ball adj grid adj array) near2 (warp or warpage or warping or warped or cte or thermal near expansion or thermally near2 expand\$3 or bending or bent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 14:57
-	28	("3248681" "3351700" "3399332" "4283464" "4491622" "4500605" "4577056" "4581680" "4712127" "4784974" "4811166" "4872047" "4888449" "4939316" "4961105" "5001546" "5015803" "5044074" "5073840" "5103292" "5213638" "5239131" "5241133" "5315155" "5409865" "5506446" "5578869" "5629835").PN.	USPAT	2004/08/12 14:41
-	27	fujitsu.asn. and umeda.in. and osamu.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/12 14:57